

Ag 接着剤 TS-9853, TS-9870

◎TS-9853

Alternative Lead in High melting temperature solders

		TS-9853		
Feature		<ul style="list-style-type: none"> • High Thermal Conductivity • Good Adhesion to bare Cu LF • Good reliability with metalized surface 		memo
Storage Condition		below -40°C in freezer		
Ag Content		89 wt %		Calculated after 850°C firing
Viscosity		20 Pa.s		E-type 3°corn, 5rpm @ RT
Thixotropic Index		7.5		0.5rpm/5rpm
Volume Resistivity		10.0 x 10 ⁻⁶ Ω·cm		Resistivity meter
Die Shear Strength	at RT	45 N/mm ²		2x2mm Si-die (BSM:Ag) / Ag plated LF
	at 260°C	17 N/mm ²		
Elastic Modulus	at RT	14,000 Mpa		Measured by DMS
	at 260°C	4,200 MPa		
Coefficient of Thermal Expansion	α 1	26 ppm/°C		Measured by TMA
	α 2	26 ppm/°C		
Tg		-		
Thermal Conductivity		130 W/m·K		Measured by Laser flash

◎TS-9870

for LED and LD

		TS-9870		
Feature		<ul style="list-style-type: none"> • High Thermal Conductivity • Good Adhesion to metalized surface • Good workability, longer tack time • 10um BLT adjustable with Ag spacer 		memo
Storage Condition		below -40°C in freezer		
Ag Content		92 wt %		Calculated after 850°C firing
Viscosity		18 Pa.s		E-type 3°corn, 5rpm @ RT
Thixotropic Index		6.5		0.5rpm/5rpm
Volume Resistivity		5 x 10 ⁻⁶ Ω·cm		Resistivity meter
Die Shear Strength	at RT	50 N/mm ²		2x2mm Si-die (BSM:Ag) / Ag plated LF
	at 260°C	30 N/mm ²		
Thermal Conductivity		160 W/m·K		Measured by Laser flash

